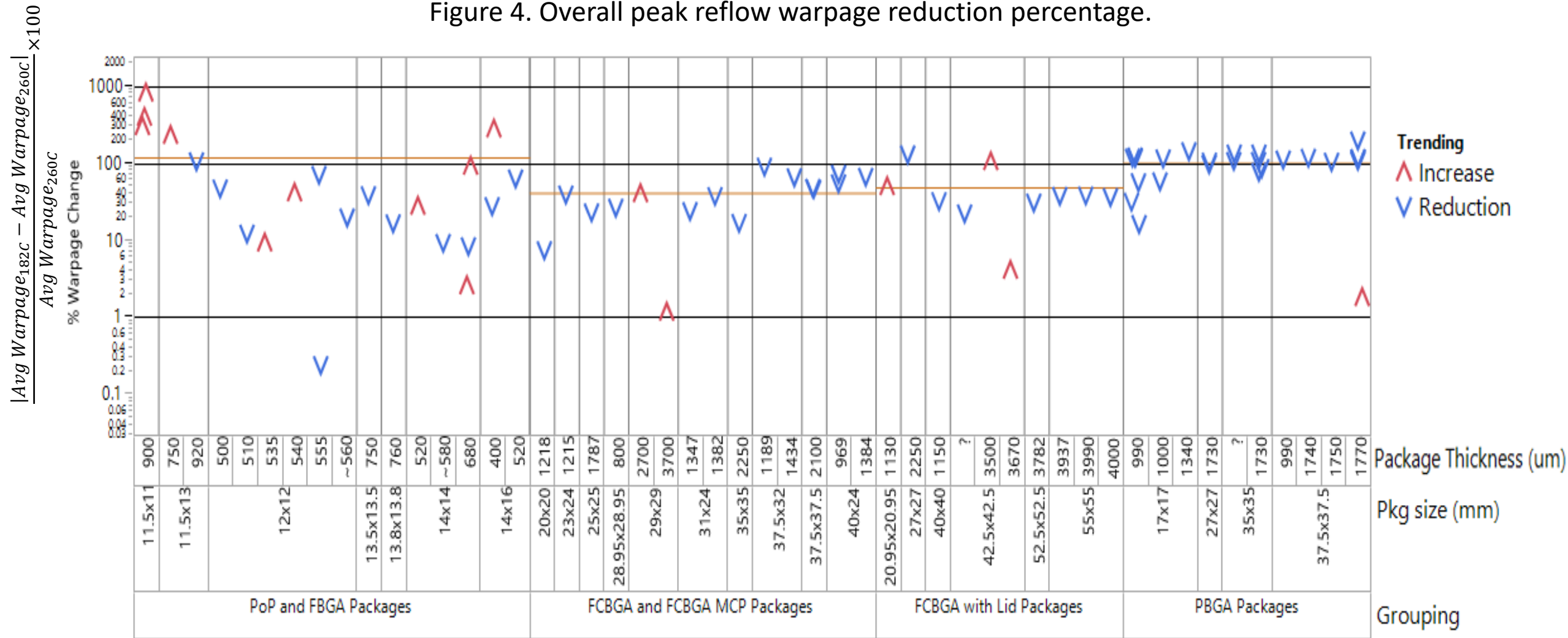


Figure 4. Overall peak reflow warpage reduction percentage.



Majority of the package warpage change is as low as 10% to about 100%. With some exception of warpage increase by factor of 10 (1000%) because of an order of magnitude lower at 260°C compared to 182°C warpage magnitude.

Majority of the package warpage change is around 20% to about 100%. Reasonable agreement of 30% to 50% warpage reduction.

Majority of the package warpage change is around 20% to about 50%.

Majority of the package warpage change is around 40% to about 250% which is attributed to the higher temperature sensitivity as a result of the higher volume of mold encapsulations used.